# MSKSEMI















**ESD** 

**TVS** 

**TSS** 

MOV

**GDT** 

**PLED** 

Broduct data speet











Ultra low leakage: nA level

Operating voltage: 5V

Low clamping voltage

• Complies with following standards:

- IEC 61000-4-2 (ESD) immunity test

Air discharge: ±15kV Contact discharge: ±8kV

- IEC61000-4-4 (EFT) 40A (5/50ns)

- IEC61000-4-5 (Lightning) 3A (8/20μs)

RoHS Compliant



USB 2.0 power and data line

Set-top box and digital TV

Digital video interface (DVI)

Notebook Computers

SIM Ports

• 10/100 Ethernet

#### **Mechanical Characteristics**

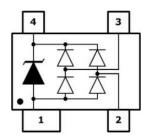
Package: SOT-143

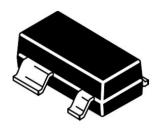
Lead Finish: Lead Free

• UL Flammability Classification Rating 94V-0

Quantity Per Reel:3,000pcs

Reel Size:7 inch





SOT-143

# **Absolute Maximum Ratings**(Tamb=25°C unless otherwise specified)

Parameter	Symbol	Value	Unit
Peak Pulse Power (8/20µs)	Ррр	300	W
ESD per IEC 61000-4-2 (Air)	V <sub>ESD</sub>	±15	Kv
ESD per IEC 61000-4-2 (Contact)	VESD	±8	IXV
Operating Temperature Range	TJ	-55 to +125	${\mathbb C}$
Storage Temperature Range	T <sub>STJ</sub>	-55 to +150	$^{\circ}$



# **Electrical Characteristics**(TA=25°C unless otherwise specified)

	V <sub>RWM</sub>	M VBR IT	l <sub>+</sub>	l+	IT	Vc	Vo	Vo	Vc		I <sub>R</sub>	С
P/N		(mA)		(Max)	(@A)	μA (Max)	(Pf) (Typ.)					
MSSR05.TCT	5	6	1	9.8	23	3	1	1.2				

### **Characteristic Curves**

Fig1.  $8/20\mu$  s Pulse Waveform

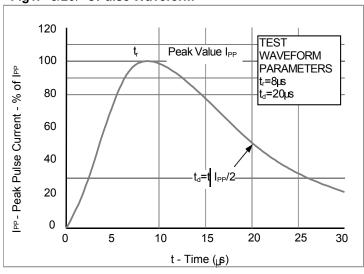


Fig2. ESD Pulse Waveform (according to IEC 61000-4-2)

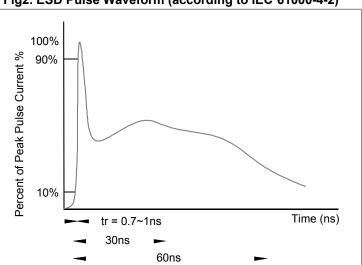
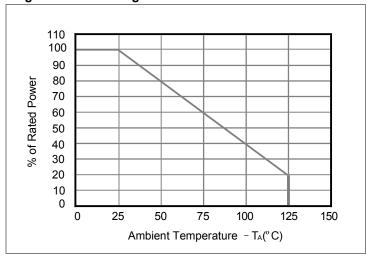


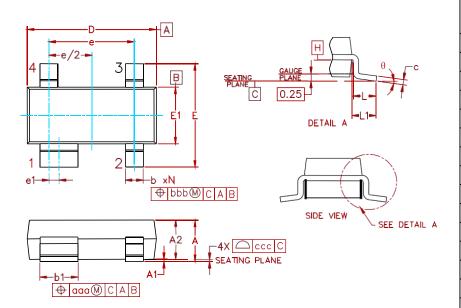
Fig3. Power Derating Curve





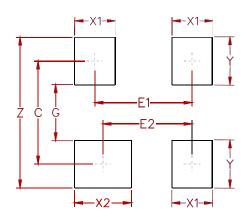


### **PACKAGE MECHANICAL DATA**



Cumbal		Inches		Millimeters			
Symbol	Min.	Nom.	Max.	Min.	Nom.	Max.	
Α	0.031	-	0.048	0.80	-	1.22	
<b>A</b> 1	0.000	-	0.008	0.013	-	0.15	
A2	0.020	0.035	0.042	0.75	0.90	1.07	
b	0.011	1	0.020	0.30	1	0.51	
b1	0.029	-	0.037	0.76	-	0.94	
С	0.003	-	0.008	0.08	-	0.20	
D	0.110	0.114	0.120	2.80	2.90	3.04	
E	0.082	0.093	0.104	2.10	2.37	2.64	
E1	0.047	0.051	0.055	1.20	1.30	1.40	
е	0.075			1.92 BSC			
e1	0.008			0.20 BSC			
٦	0.015	0.020	0.024	0.40	0.50	0.60	
L1	(0.021)			(0.54)			
N	4			4			
Ф	0°	1	8°	0°	1	8°	
aaa	0.006			0.15			
bbb	0.008			0.20			
ССС	0.004			0.10			

## **Suggested Pad Layout**



#### **REEL SPECIFICATION**

P/N	PKG	QTY
MSSR05.TCT	SOT-143	3000



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